

TPS38x -Q1 (65 V & 2uA) Wide V_{IN} Dual Channel Voltage Detector

1 Features

- AEC-Q100 qualified with the following results:
 - Device temperature grade 1: -40°C to +125°C ambient operating temperature
 - Device HBM ESD classification level 2
 - Device CDM ESD classification level C7B
- VDD: 2.7 V to 65 V (V_{POR}=1.4 V)
- SENSE and RESET pins are 65 V graded
- Low supply current: 1 µA (Typ.)
- Flexible voltage option [Table 14-2](#)
 - 2.7 V to 36 V (1.5% max accuracy)
 - 800 mV option (1% max accuracy)
- Built-in hysteresis (V_{HYS})
 - Percentage options: 2% to 13% (1% steps)
 - Fixed options: V_{TH} < 8 V = 0.5 V, 1 V, 1.5 V, 2 V, 2.5 V
- Programmable reset time delay
 - 10 nF = 12.8 ms, 10 µF = 12.8 s
- Programmable sense time delay
 - 10 nF = 1.28 ms, 10 µF = 1.28 s
- Manual reset feature
- Output reset latching feature
- Output topology:
 - Channel 1: Open-Drain or Push-Pull topologies
 - Channel 2: Open-Drain

2 Applications

- [Telematics control unit](#)
- [Emergency call system](#)
- [Audio amplifier](#)
- [Head unit and cluster](#)
- [Sensor fusion and cameras](#)
- [Body control module](#)

3 Description

The TPS38x-Q1 is a 65 V-input voltage detector with 1 µA I_{DD}, 1% accuracy, and 10 µs detection time in a 6.25 mm² package. This device can be connected directly to 12 V / 24 V automotive battery system for continuous monitoring of over (OV) and under (UV) voltage conditions; with its internal resistor divider, it offers the smallest total solution size. Wide hysteresis voltage options are available to ignore cold crank, start-stop and various car battery voltage transients. Built-in hysteresis on the SENSE pins prevents false reset signals when monitoring a supply voltage rail.

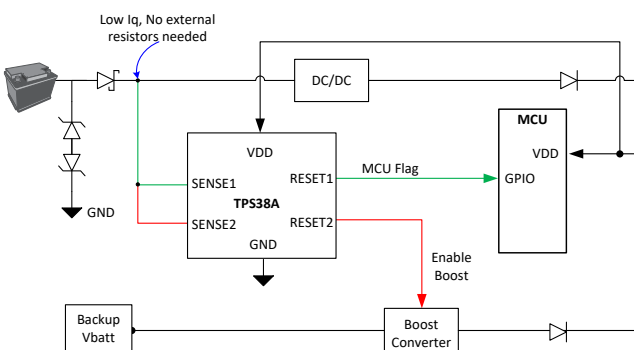
The separate VDD and SENSE pins allow for the redundancy sought by high-reliability automotive systems and SENSE can monitor higher and lower voltages than VDD. Optional use of external resistors are supported by the high impedance input of the SENSE pins. Both CTSx and CTRx provide delay adjustability on the rising and falling edges of the RESET signals. Also, CTSx functions as a debouncer by ignoring voltage glitches on the monitored voltage rails; CTRx operates as a manual reset (\overline{MR}) that can be used to force a system reset.

The TPS38x-Q1 is available in a small 2.5-mm×2.5-mm×0.1-mm WSON 10-pin wettable flanks package allowing the facilitation for Automatic Optical Inspection (AOI) and low resolution X-ray inspection. The central pad is non-conductive to increase the creepage between VDD and GND per guidelines in IEC60664. TPS38x-Q1 operates over -40°C to +125°C (T_A).

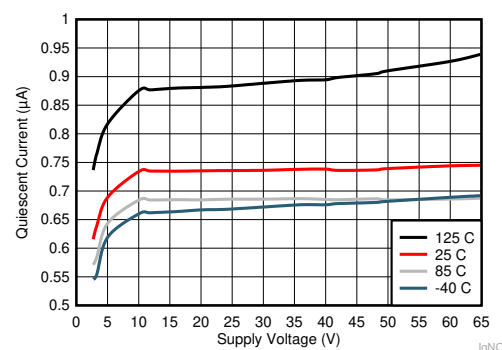
Device Information

PART NUMBER	PACKAGE ⁽¹⁾	BODY SIZE (NOM)
TPS38x-Q1	WSON-10 (DSK)	2.5 mm × 2.5 mm

- (1) For package details, see the mechanical drawing addendum at the end of the data sheet.



Typical Application Circuit



Typical Supply Current vs VDD



Table of Contents

1 Features	1	11 Application and Implementation	22
2 Applications	1	11.1 Adjustable Voltage Thresholds.....	22
3 Description	1	11.2 Application Information.....	22
4 Revision History	2	11.3 Typical Application.....	23
5 Device Comparison	3	12 Power Supply Recommendations	25
6 Pin Configuration and Functions	4	12.1 Power Dissipation and Device Operation.....	25
7 Specifications	8	13 Layout	26
7.1 Absolute Maximum Ratings	8	13.1 Layout Guidelines.....	26
7.2 ESD Ratings	8	13.2 Layout Example.....	26
7.3 Recommended Operating Conditions	8	13.3 Creepage Distance.....	26
7.4 Thermal Information	8	14 Device and Documentation Support	27
7.5 Electrical Characteristics	9	14.1 Device Nomenclature.....	27
7.6 Timing Requirements	11	14.2 Support Resources.....	29
8 Typical Characteristics	12	14.3 Trademarks.....	29
9 Detailed Description	13	14.4 Electrostatic Discharge Caution.....	29
9.1 Overview.....	13	14.5 Glossary.....	29
9.2 Functional Block Diagram.....	13	15 Mechanical, Packaging, and Orderable Information	29
9.3 Feature Description.....	14		
10 Device Functional Modes	21		

4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (August 2020) to Revision A (January 2021)	Page
• APL Update.....	1
• Added Typical Supply Current vs VDD Curve and modified Description section.....	1
• Edited both Power Cycle figures (SENSE Outside and Within Nominal Voltage).....	14
• Corrected the Hysteresis titles for both Undervoltage figures.....	16
• Added reset time delay discharge guideline.....	18
• Added sense time delay discharge guideline.....	19
• Added Device Functional Modes tables.....	21

5 Device Comparison

Contact TI sales representatives or consult TI's E2E forum for details and availability; minimum order quantities may apply.

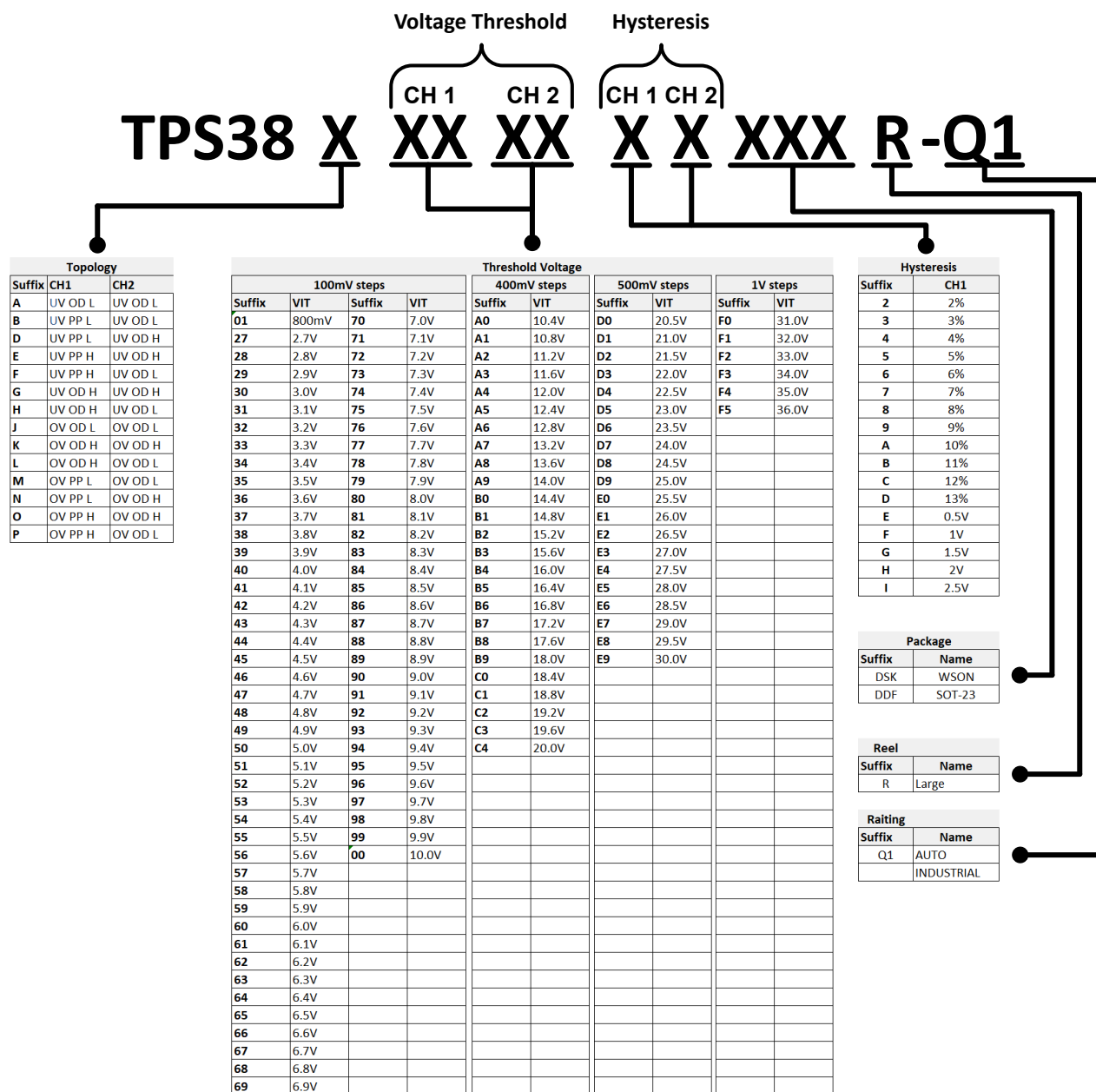


Figure 5-1. Device Nomenclature

1. Sense logic: OV = overvoltage; UV = undervoltage
2. Reset topology: PP = Push-Pull; OD = Open-Drain
3. Reset logic: L = Active-Low; H = Active-High
4. A to I hysteresis options are only available for 2.9 V to 9 V threshold options

6 Pin Configuration and Functions

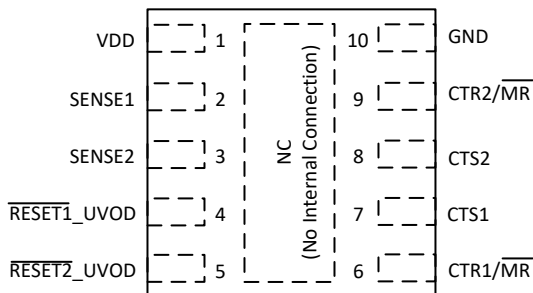


Figure 6-1. DSK Package 10-Pin WSON TPS38A (Top View)

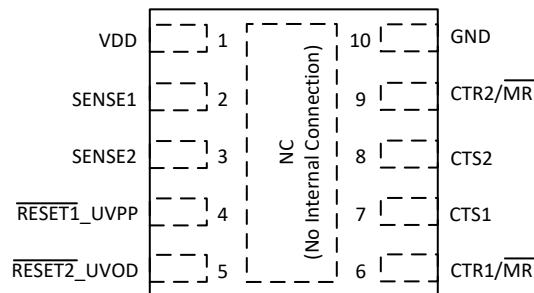


Figure 6-2. DSK Package 10-Pin WSON TPS38B (Top View)

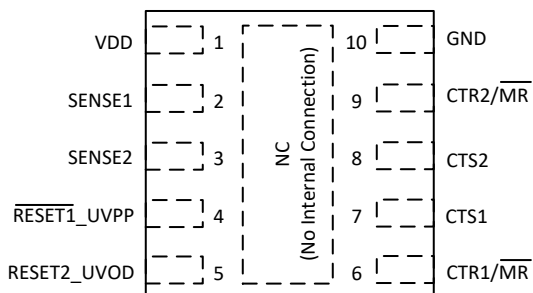


Figure 6-3. DSK Package 10-Pin WSON TPS38D (Top View)

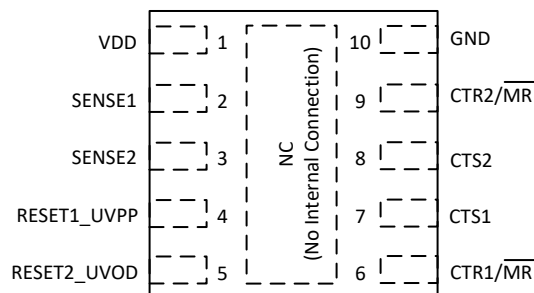


Figure 6-4. DSK Package 10-Pin WSON TPS38E (Top View)

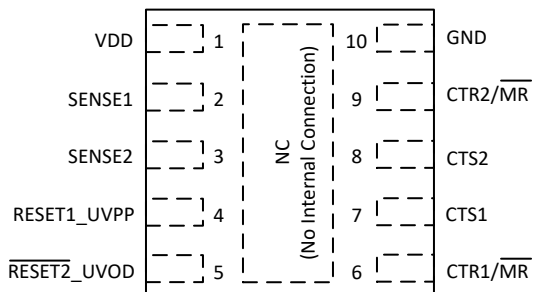


Figure 6-5. DSK Package 10-Pin WSON TPS38F (Top View)

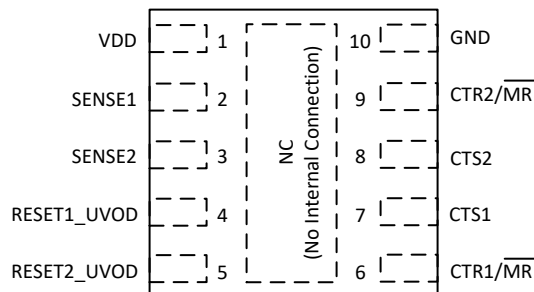


Figure 6-6. DSK Package 10-Pin WSON TPS38G (Top View)

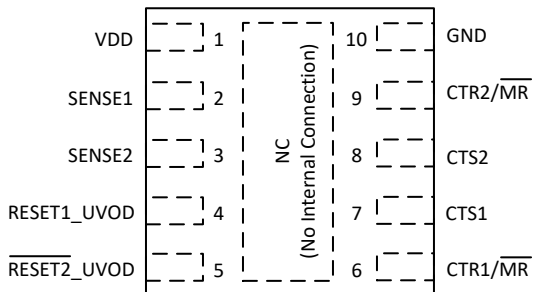


Figure 6-7. DSK Package 10-Pin WSON TPS38H (Top View)

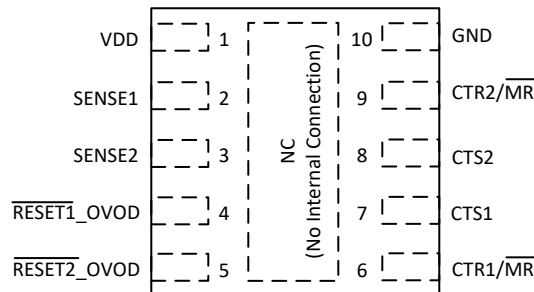


Figure 6-8. DSK Package 10-Pin WSON TPS38J (Top View)

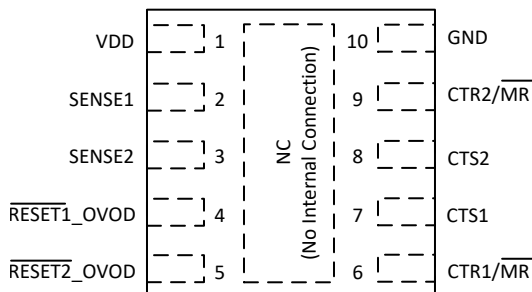


Figure 6-9. DSK Package 10-Pin WSON TPS38K (Top View)

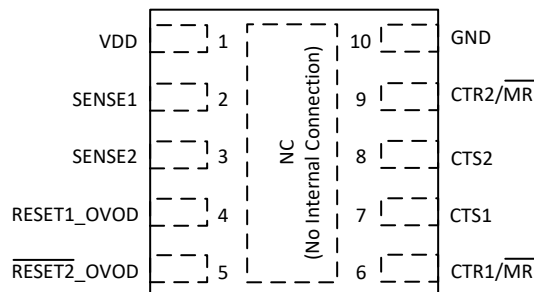


Figure 6-10. DSK Package 10-Pin WSON TPS38L (Top View)

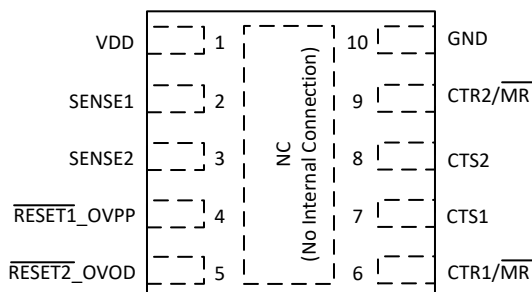


Figure 6-11. DSK Package 10-Pin WSON TPS38M (Top View)

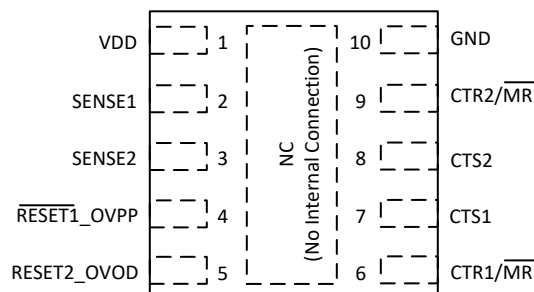


Figure 6-12. DSK Package 10-Pin WSON TPS38N (Top View)

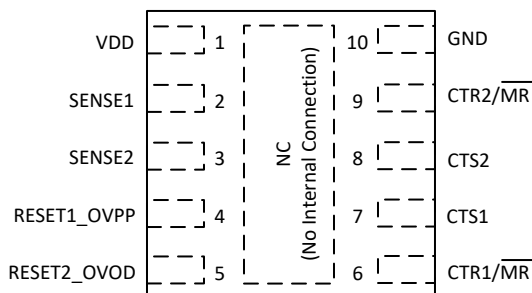


Figure 6-13. DSK Package 10-Pin WSON TPS38O (Top View)

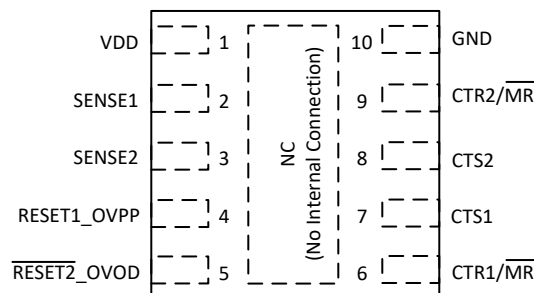


Figure 6-14. DSK Package 10-Pin WSON TPS38P (Top View)

Table 6-1. Pin Functions Generic

PIN NAME	NO.	I/O	DESCRIPTION
VDD	1	I	Input Supply Voltage.
SENSE1	2	I	Input for the monitored supply voltage rail channel 1
SENSE2	3	I	Input for the monitored supply voltage rail channel 2
RESET1 RESET1,	4	O	Output Reset Signal For Channel 1: See Figure 5-1
RESET2 RESET2,	5	O	Output Reset Signal For Channel 2: See Figure 5-1
CTR1/ $\overline{\text{MR}}$	6	—	<p>Capacitor Time Delay Reset 1. The CTR1 pin offers a user-programmable reset release delay for Reset1. Connect an external capacitor on this pin to adjust time delay. When not in use leave pin floating for the fastest time delay.</p> <p>Manual Reset (CTR1/ $\overline{\text{MR}}$): If this pin is driven low the RESET1 output will reset, leave pin floating or connected to a cap to release reset. This pin should not be driven high.</p>

Table 6-1. Pin Functions Generic (continued)

PIN NAME	NO.	I/O	DESCRIPTION
CTR2/ $\overline{\text{MR}}$	9	–	Capacitor Time Delay Reset 2. The CTR2 pin offers a user-programmable reset release delay for Reset2. Connect an external capacitor on this pin to adjust time delay. When not in use leave pin floating for the fastest time delay. Manual Reset (CTR2/ $\overline{\text{MR}}$): If this pin is driven low the RESET2 output will reset, leave pin floating or connected to a cap to release reset. This pin should not be driven high.
GND	10	–	Ground
NC	PAD	–	Not internally connected, is recommended to leave the central pad floating for wider creepage between VDD and GND.
CTS1	7	–	Capacitor Time Delay Sense 1. The CTS1 pin offers a user-programmable sense delay for Sense1. Connect an external capacitor on this pin to adjust time delay. When not in use leave pin floating for the fastest time delay.
CTS2	8	–	Capacitor Time Delay Sense 2. The CTS2 pin offers a user-programmable sense delay for Sense2. Connect an external capacitor on this pin to adjust time delay. When not in use leave pin floating for the fastest time delay.
TPS38A			
RESET1_UVOD	4	O	Reset output signal for Sense 1. Topology: Undervoltage, Open Drain, Active Low topology.
RESET2_UVOD	5	O	Reset output signal for Sense 2. Topology: Undervoltage, Open Drain, Active Low topology.
TPS38B			
RESET1_UVPP	4	O	Reset output signal for Sense 1. Topology: Undervoltage, Push Pull, Active Low topology.
RESET2_UVOD	5	O	Reset output signal for Sense 2. Topology: Undervoltage, Open Drain, Active Low topology.
TPS38D			
RESET1_UVPP	4	O	Reset output signal for Sense 1. Topology: Undervoltage, Push Pull, Active Low topology.
RESET2_UVOD	5	O	Reset output signal for Sense 2. Topology: Undervoltage, Open Drain, Active High topology.
TPS38E			
RESET1_UVPP	4	O	Reset output signal for Sense 1. Topology: Undervoltage, Push Pull, Active High topology.
RESET2_UVOD	5	O	Reset output signal for Sense 2. Topology: Undervoltage, Open Drain, Active High topology.
TPS38F			
RESET1_UVPP	4	O	Reset output signal for Sense 1. Topology: Undervoltage, Push Pull, Active High topology.
RESET2_UVOD	5	O	Reset output signal for Sense 2. Topology: Undervoltage, Open Drain, Active Low topology.
TPS38G			
RESET1_UVOD	4	O	Reset output signal for Sense 1. Topology: Undervoltage, Open Drain, Active High topology.
RESET2_UVOD	5	O	Reset output signal for Sense 2. Topology: Undervoltage, Open Drain, Active High topology.
TPS38H			
RESET1_UVOD	4	O	Reset output signal for Sense 1. Topology: Undervoltage, Open Drain, Active High topology.
RESET2_UVOD	5	O	Reset output signal for Sense 2. Topology: Undervoltage, Open Drain, Active Low topology.
TPS38J			
RESET1_OVOD	4	O	Reset output signal for Sense 1. Topology: Overvoltage, Open Drain, Active Low topology.
RESET2_OVOD	5	O	Reset output signal for Sense 2. Topology: Overvoltage, Open Drain, Active Low topology.
TPS38K			
RESET1_OVOD	4	O	Reset output signal for Sense 1. Topology: Overvoltage, Open Drain, Active High topology.
RESET2_OVOD	5	O	Reset output signal for Sense 2. Topology: Overvoltage, Open Drain, Active High topology.
TPS38L			
RESET1_OVOD	4	O	Reset output signal for Sense 1. Topology: Overvoltage, Open Drain, Active High topology.
RESET2_OVOD	5	O	Reset output signal for Sense 2. Topology: Overvoltage, Open Drain, Active Low topology.
TPS38M			
RESET1_OVPP	4	O	Reset output signal for Sense 1. Topology: Overvoltage, Push Pull, Active Low topology.
RESET2_OVOD	5	O	Reset output signal for Sense 2. Topology: Overvoltage, Open Drain, Active Low topology.

Table 6-1. Pin Functions Generic (continued)

PIN			
NAME	NO.	I/O	DESCRIPTION
TPS38N			
RESET1_OVPP	4	O	Reset output signal for Sense 1. Topology: Overvoltage, Push Pull, Active Low topology.
RESET2_OVOD	5	O	Reset output signal for Sense 2. Topology: Overvoltage, Open Drain, Active High topology.
TPS38O			
RESET1_OVPP	4	O	Reset output signal for Sense 1. Topology: Overvoltage, Push Pull, Active High topology.
RESET2_OVOD	5	O	Reset output signal for Sense 2. Topology: Overvoltage, Open Drain, Active High topology.
TPS38P			
RESET1_OVPP	4	O	Reset output signal for Sense 1. Topology: Overvoltage, Push Pull, Active High topology.
RESET2_OVOD	5	O	Reset output signal for Sense 2. Topology: Overvoltage, Open Drain, Active Low topology.

7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range, unless otherwise noted⁽¹⁾

		MIN	MAX	UNIT
Voltage	V _{DD} , V _{SENSE1} , V _{SENSE2} , V _{RESET1} , V _{RESET2} , V _{RESET1} , V _{RESET2}	−0.3	70	
Voltage	V _{CTS1} , V _{CTS2} , V _{CTR1} , V _{CTR2}	−0.3	6	
Current	I _{RESET1} , I _{RESET2} , I _{RESET1} , I _{RESET2}		10	mA
Temperature ⁽²⁾	Operating junction temperature, T _J	−40	150	°C
Temperature ⁽²⁾	Operating Ambient temperature, T _A	−40	150	°C
Temperature ⁽²⁾	Storage, T _{stg}	−65	150	°C

- (1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) As a result of the low dissipated power in this device, it is assumed that T_J = T_A.

7.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per AEC Q100-002 ⁽¹⁾	±2000	V
		Charged device model (CDM), per AEC Q100-011	±750	

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Voltage	V _{DD}	2.7		65	V
Voltage	V _{SENSE1} , V _{SENSE2} , V _{RESET1} , V _{RESET2} , V _{RESET1} , V _{RESET2}	0		65	V
Voltage	V _{CTS1} , V _{CTS2} , V _{CTR1} , V _{CTR2}	0		5.5	V
Current	I _{RESET1} , I _{RESET2} , I _{RESET1} , I _{RESET2}	0		±5	mA
T _J	Junction temperature (free air temperature)	−40		125	°C

7.4 Thermal Information

THERMAL METRIC ⁽¹⁾		DSK	UNIT
		10-PIN	
R _{θJA}	Junction-to-ambient thermal resistance	87.4	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	76.3	°C/W
R _{θJB}	Junction-to-board thermal resistance	54.2	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	4.8	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	54.2	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	34.8	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

7.5 Electrical Characteristics

At $V_{DD(MIN)} \leq V_{DD} \leq V_{DD(MAX)}$, $CTR1 / \overline{MR} = CTR2 / \overline{MR} = CTS1 = CTS2 = \text{Open}$, Output reset Pullup Resistor (R_{PULLUP}) = 10 k Ω , Output reset Pullup Voltage (V_{PULLUP}) = 5.5 V, output reset load (C_{LOAD}) = 10 pF and over the operating free-air temperature range – 40°C to 125°C, unless otherwise noted. Typical values are at $T_J = 25^\circ\text{C}$ and $V_{DD} = 16\text{ V}$ and $V_{IT} = 6.5\text{ V}$ (V_{IT} refers to V_{ITN} or V_{ITP}).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
VDD						
V _{DD}	Supply Voltage		2.7		65	V
UVLO ⁽²⁾	Under Voltage Lockout	V _{DD} Falling below V _{DD} (MIN)			2.7	V
V _{POR}	Power on Reset Voltage ⁽⁵⁾ RESET, Active Low (Open-Drain, Push-Pull)	V _{OL} (max) = 300 mV I _{OUT} (Sink) = 15 μA			1.4	V
V _{POR}	Power on Reset Voltage ⁽⁵⁾ RESET, Active High (Push-Pull)	V _{OH} (min) = 0.8 x V _{DD} I _{OUT} (Source) = 15 μA			1.4	V
I _{DD}	Supply current into VDD pin	V _{IT} = 800 mV V _{DD} (MIN) ≤ V _{DD} ≤ V _{DD} (MAX)		1	2.6	μA
		V _{IT} = 2.7 V to 36 V V _{DD} (MIN) ≤ V _{DD} ≤ V _{DD} (MAX)		1	2	μA
SENSE (Input)						
I _{SENSE}	Input current (SENSE1, SENSE2)	V _{IT} = 800 mV			100	nA
I _{SENSE}	Input current (SENSE1, SENSE2)	V _{IT} < 10 V			0.8	uA
I _{SENSE}	Input current (SENSE1, SENSE2)	10 V < V _{IT} < 26 V			1.2	uA
I _{SENSE}	Input current (SENSE1, SENSE2)	V _{IT} > 26 V			2	uA
V _{ITN}	Input Threshold Negative (Under-Voltage)	V _{IT} = 2.7 V to 36 V	-1.5		1.5	%
		V _{IT} = 800 mV ⁽³⁾	0.792	0.800	0.808	V
V _{ITP}	Input Threshold Positive (Over-Voltage)	V _{IT} = 2.7 V to 36 V	-1.5		1.5	%
		V _{IT} = 800 mV ⁽³⁾	0.792	0.800	0.808	V
V _{HYS}	Hysteresis Accuracy ⁽¹⁾	V _{IT} = 0.8 V and 2.7 V to 36 V V _{HYS} Range = 2% to 13% (1% step)	-1.5		1.5	%
		V _{IT} = 2.7 V to 8 V V _{HYS} = 0.5 V, 1 V, 1.5 V, 2 V, 2.5 V V _{IT} -V _{HYS} ≥ 2.4 V	-1.5		1.5	%
RESET (output)						
I _{lkg} (OD)	Open-Drain leakage (RESET1, RESET2)	V _{RESET} = 5.5 V V _{ITN} < V _{SENSE} < V _{ITP}			300	nA
		V _{RESET} = 65 V V _{ITN} < V _{SENSE} < V _{ITP}			300	nA
V _{OL} ⁽⁴⁾	Low level output voltage	2.7 V ≤ V _{DD} ≤ 65 V I _{RESET} = 5 mA			300	mV
V _{OH_DO}	High level output voltage dropout (V _{DD} - V _{OH} = V _{OH_DO}) (Push-Pull only)	2.7 V ≤ V _{DD} ≤ 65 V I _{RESET} = 500 uA			43	mV
V _{OH} ⁽⁴⁾	High level output voltage (Push-Pull only)	2.7 V ≤ V _{DD} ≤ 65 V I _{RESET} = 5 mA	0.8V _{DD}			V

7.5 Electrical Characteristics (continued)

At $V_{DD(MIN)} \leq V_{DD} \leq V_{DD(MAX)}$, $CTR1 / \overline{MR} = CTR2 / \overline{MR} = CTS1 = CTS2 = \text{Open}$, Output reset Pullup Resistor (R_{PULLUP}) = 10 k Ω , Output reset Pullup Voltage (V_{PULLUP}) = 5.5 V, output reset load (C_{LOAD}) = 10 pF and over the operating free-air temperature range – 40°C to 125°C, unless otherwise noted. Typical values are at $T_J = 25^\circ\text{C}$ and $V_{DD} = 16\text{ V}$ and $V_{IT} = 6.5\text{ V}$ (V_{IT} refers to V_{ITN} or V_{ITP}).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Capacitor Timing (CTS, CTR)						
R_{CTR}	Internal resistance ($CTR1 / \overline{MR}$, $CTR2 / \overline{MR}$)		877	1000	1147	Kohms
R_{CTS}	Internal resistance ($CTS1$, $CTS2$)		88	100	122	Kohms
Manual Reset (MR)						
V_{MR_IH}	$CTR1 / \overline{MR}$ and $CTR2 / \overline{MR}$ pin logic high input	$V_{DD} = 2.7\text{ V}$	2000			mV
V_{MR_IH}	$CTR1 / \overline{MR}$ and $CTR2 / \overline{MR}$ pin logic high input	$V_{DD} = 65\text{ V}$	2500			mV
V_{MR_IL}	$CTR1 / \overline{MR}$ and $CTR2 / \overline{MR}$ pin logic low input	$V_{DD} = 2.7\text{ V}$			1300	mV
V_{MR_IL}	$CTR1 / \overline{MR}$ and $CTR2 / \overline{MR}$ pin logic low input	$V_{DD} = 65\text{ V}$			1300	mV

- (1) Hysteresis is with respect to V_{ITP} and V_{ITN} voltage threshold. V_{ITP} has negative hysteresis and V_{ITN} has positive hysteresis.
- (2) When V_{DD} voltage falls below UVLO, reset is asserted for Output 1 and Output 2. V_{DD} slew rate $\leq 100\text{mV}/\mu\text{s}$
- (3) For adjustable voltage guidelines and resistor selection refer to **Adjustable Voltage Thresholds** in **Application and Implementation section**
- (4) For V_{OH} and V_{OL} relation to output variants refer to **Timing Figures after the Timing Requirement Table**
- (5) V_{POR} is the minimum V_{DD} voltage for a controlled output state. Below V_{POR} , the output cannot be determined. V_{DD} $dv/dt \leq 100\text{mV}/\mu\text{s}$

7.6 Timing Requirements

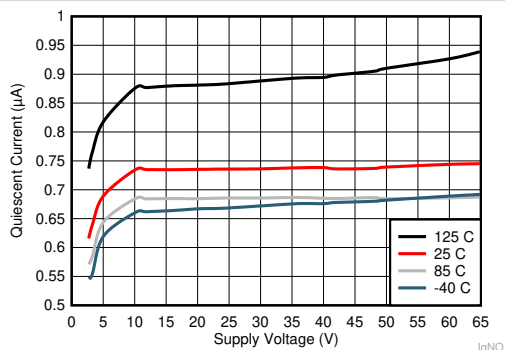
At $V_{DD_MIN} \leq V_{DD} \leq V_{DD_MAX}$, $CTR1/\overline{MR} = CTR2/\overline{MR} = CTS1 = CTS2 = \text{Open}$ ⁽¹⁾, Output reset Pullup Resistor (R_{PULLUP}) = 10 k Ω , Output reset Pullup Voltage (V_{PULLUP}) = 5.5V, output reset load (C_{LOAD}) = 10 pF, VDD and SENSE slew rate = 1V/ μ s, over the operating free-air temperature range – 40°C to 125°C, unless otherwise noted. Typical values are at $T_J = 25^\circ\text{C}$ and $V_{DD}=16\text{ V}$ and $V_{IT} = 6.5\text{ V}$ (V_{IT} refers to either V_{ITN} or V_{ITP}).

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Common timing parameters					
t_{CTR}	Reset release time delay ($CTR1/\overline{MR}$, $CTR2/\overline{MR}$) ⁽³⁾	VIT = 2.7 V to 36 V $C_{TR1} = C_{TR2} = \text{Open}$ 20% Overdrive from Hysteresis		100	μ s
		VIT = 800 mV $C_{TR1} = C_{TR2} = \text{Open}$ 20% Overdrive from Hysteresis		40	μ s
t_{CTS}	Sense detect time delay ($CTS1$, $CTS2$) ⁽⁴⁾	VIT = 2.7 V to 36 V $C_{TS1} = C_{TS2} = \text{Open}$ 20% Overdrive from V_{IT}		34	90 μ s
		VIT = 800 mV $C_{TS1} = C_{TS2} = \text{Open}$ 20% Overdrive from V_{IT}		8	11 μ s
t_{SD}	Startup Delay ⁽²⁾	$C_{TR1}/\overline{MR} = C_{TR2} = \text{Open}$		2	ms

- (1) C_{TR1} = Reset delay channel 1, C_{TR2} = Reset delay channel 2,
 C_{TS1} = Sense delay channel 1, C_{TS2} = Sense delay channel 2
- (2) During the power-on sequence, VDD must be at or above VDD (MIN) for at least t_{SD} before the output is in the correct state based on V_{SENSE} .
 t_{SD} time includes the propagation delay ($C_{TR1} = C_{TR2} = \text{Open}$). Capacitor in C_{TR1} or C_{TR2} will add time to t_{SD} .
- (3) **CTR Reset detect time delay:**
OVER-voltage active-LOW output is measure from $V_{ITP} - HYS$ to V_{OH}
UNDER-voltage active-LOW output is measure from $V_{ITN} + HYS$ to V_{OH}
OVER-voltage active-HIGH output is measure from $V_{ITP} - HYS$ to V_{OL}
UNDER-voltage active-HIGH output is measure from $V_{ITN} + HYS$ to V_{OL}
- (4) **CTS Sense detect time delay:**
Active-low output is measure from V_{IT} to V_{OL} (or V_{PULLUP})
Active-high output is measured from V_{IT} to V_{OH}
 V_{IT} refers to either V_{ITN} or V_{ITP}

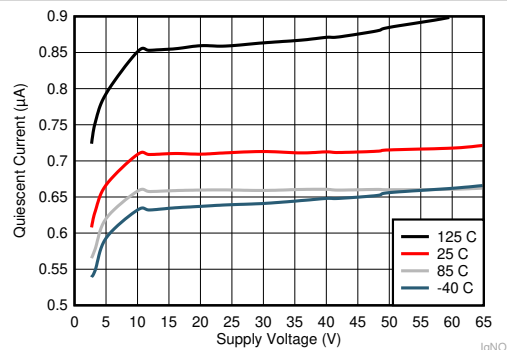
8 Typical Characteristics

Typical characteristics show the typical performance of the TPS38x device. Test conditions are $T_J = 25^\circ\text{C}$, $R_{\text{pull-up}} = 100\text{ k}\Omega$, $C_{\text{Load}} = 50\text{ pF}$, unless otherwise noted.



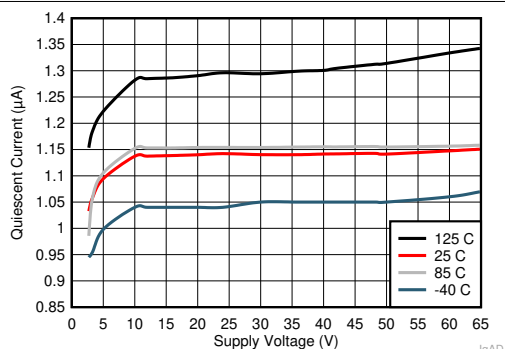
RESET = high, $V_{IT} = 2.7\text{V}$

Figure 8-1. Supply Voltage (V_{DD}) vs Supply Current (I_{DD}) over Temperature



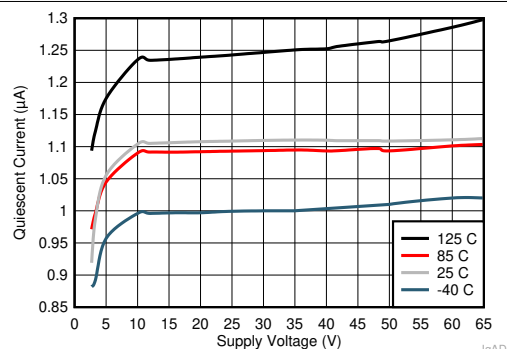
RESET = low, $V_{IT} = 2.7\text{V}$

Figure 8-2. Supply Voltage (V_{DD}) vs Supply Current (I_{DD}) over Temperature



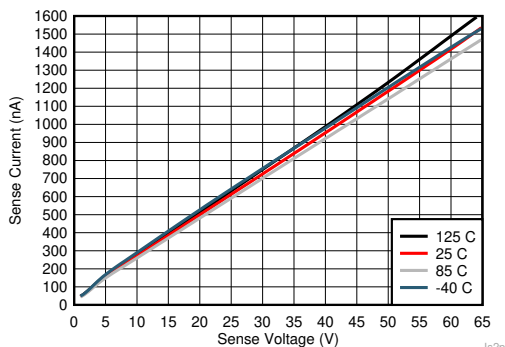
RESET = high, $V_{IT} = 0.8\text{V}$

Figure 8-3. Supply Voltage (V_{DD}) vs Supply Current (I_{DD}) over Temperature



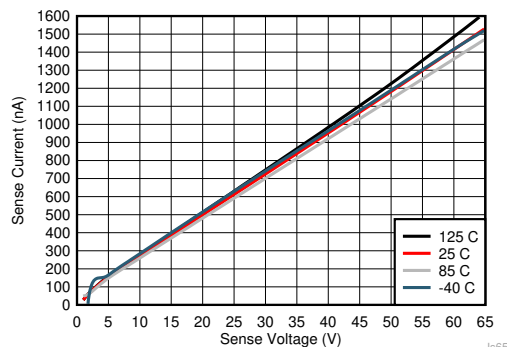
RESET = low, $V_{IT} = 0.8\text{V}$

Figure 8-4. Supply Voltage (V_{DD}) vs Supply Current (I_{DD}) over Temperature



$V_{DD} = 2.7\text{V}$

Figure 8-5. Sense Voltage (V_{SENSE}) vs Sense Current (I_{SENSE}) over Temperature



$V_{DD} = 65\text{V}$

Figure 8-6. Sense Voltage (V_{SENSE}) vs Sense Current (I_{SENSE}) over Temperature

9 Detailed Description

9.1 Overview

The TPS38x is a family of high voltage and low quiescent current reset IC with fixed threshold voltage. Voltage divider is integrated to eliminate the need for external resistors and eliminate leakage current that comes with resistor dividers. However, it can also support external resistor if required by application, the lowest threshold 800 mV (bypass internal resistor ladder) is recommended for external resistors use case to take advantage of faster detection time and lower I_{SENSE} current.

VDD, SENSE and RESET pins can support 65 V continuous operation; both VDD and SENSE voltage levels can be independent of each other, meaning VDD pin can be connected at 2.7 V while SENSE pins are connected to a higher voltage.

Additional features include programmable sense time delay (CTS1, CTS2) and reset delay time and manual reset (CTR1/MR, CTR2/MR).

9.2 Functional Block Diagram

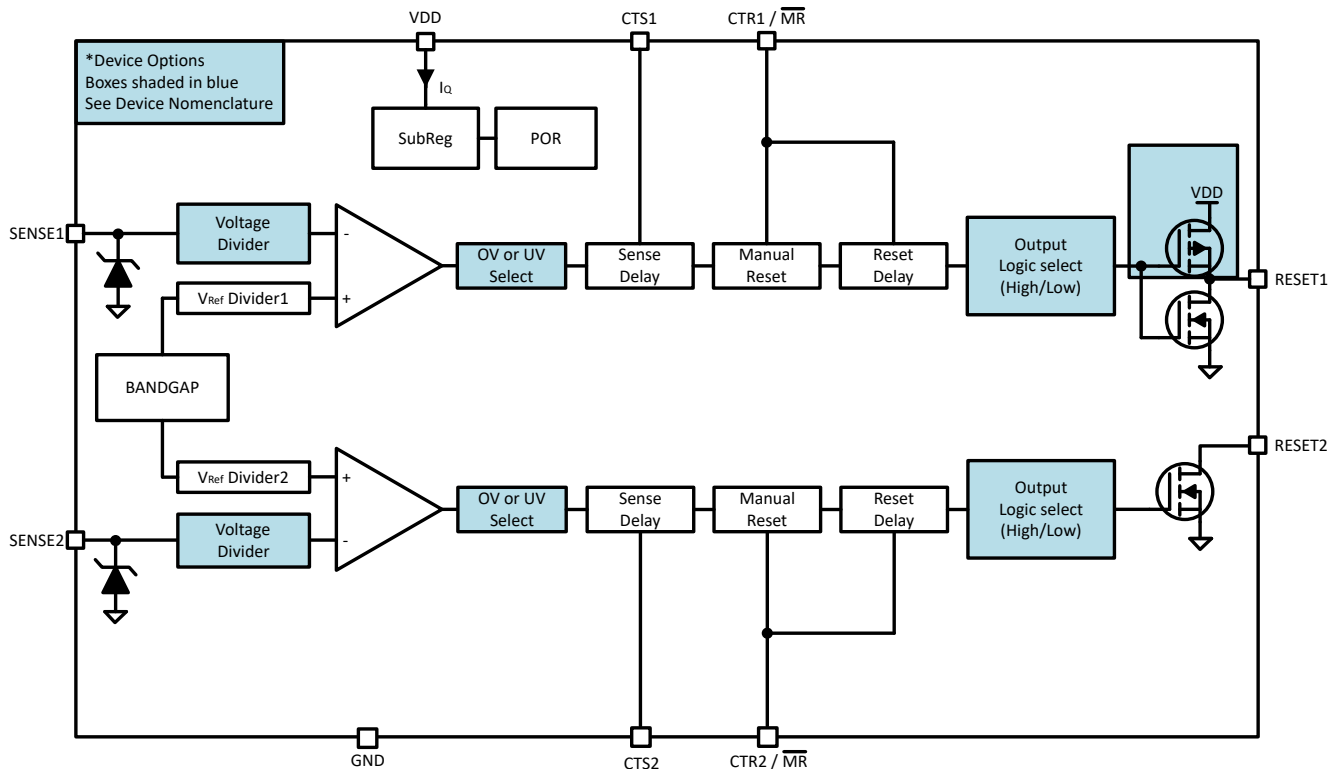


Figure 9-1. Functional Block Diagram ¹

¹ To see all possible output topology combination refer to [Section 5](#)

9.3 Feature Description

9.3.1 Input Voltage (VDD)

VDD operating voltage ranges from 2.7 V to 65 V. An input supply capacitor is not required for this device; however, if the input supply is noisy good analog practice is to place a 0.1-μF capacitor between the VDD and GND.

VDD needs to be at or above $V_{DD(MIN)}$ for at least the start-up time delay (t_{SD}) for the device to be fully functional.

VDD voltage is independent of V_{SENSE} and V_{RESET} , meaning that VDD can be higher or lower than the other pins.

9.3.1.1 Undervoltage Lockout ($V_{POR} < V_{DD} < UVLO$)

When the voltage on VDD is less than the UVLO voltage, but greater than the power-on reset voltage (V_{POR}), the output pins will be in reset, regardless of the voltage at SENSE pins.

9.3.1.2 Power-On Reset ($V_{DD} < V_{POR}$)

When the voltage on VDD is lower than the power on reset voltage (V_{POR}), the output signal is undefined and is not to be relied upon for proper device function.

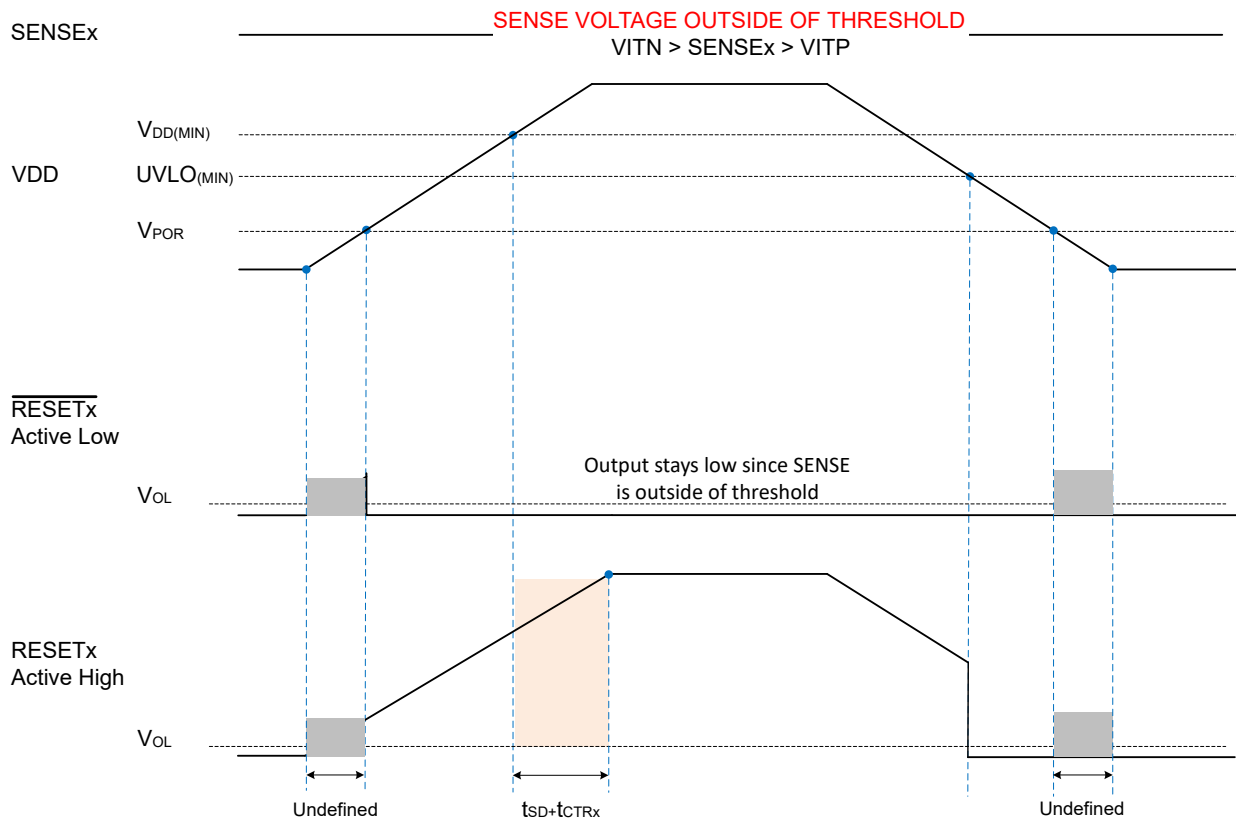


Figure 9-2. Power Cycle (SENSE Outside of Nominal voltage) ²

² Figure assume Pull-up resistor connected to VDD

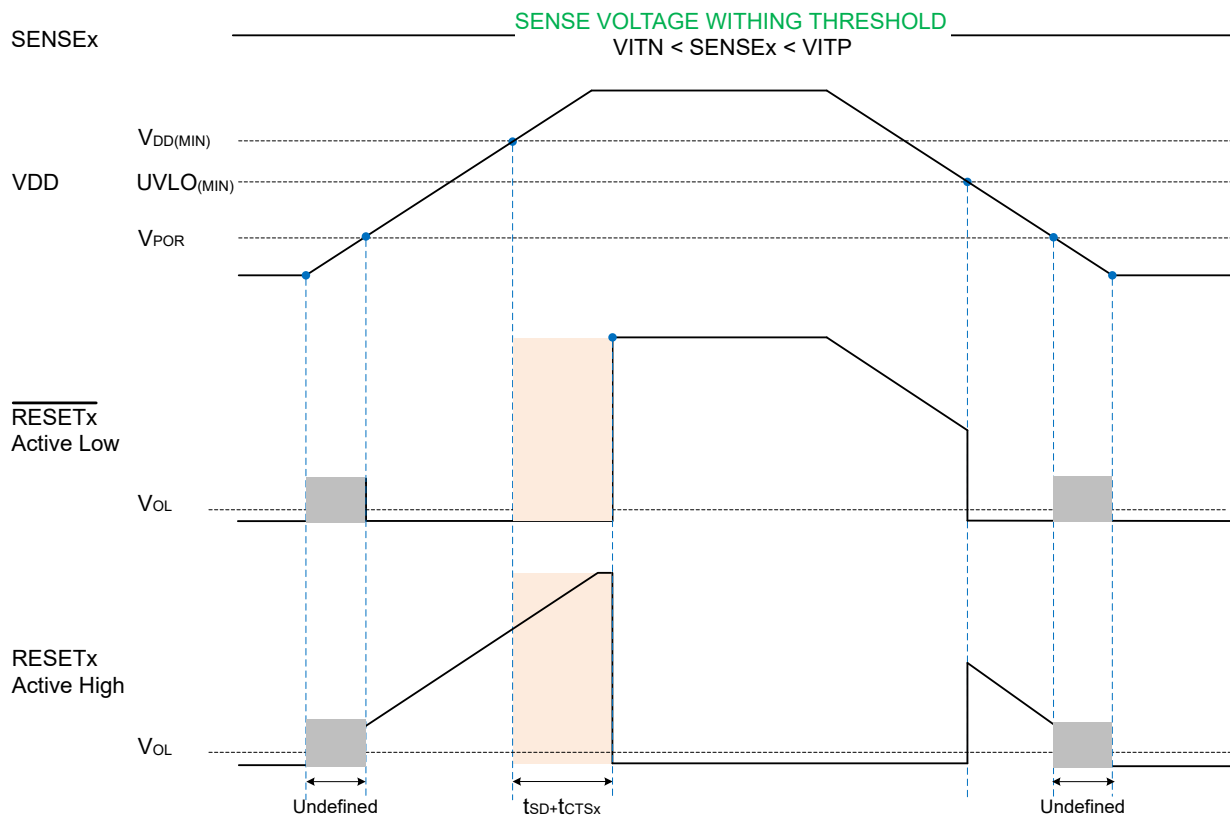


Figure 9-3. Power Cycle (SENSE Within Nominal voltage)³

³ Figure assume Pull-up resistor connected to VDD

9.3.2 SENSE

The TPS38x high voltage family integrates two voltage comparators, a precision reference voltage and trimmed resistor divider. This configuration optimizes device accuracy because all resistor tolerances are accounted for in the accuracy and performance specifications. Device also has built-in hysteresis that provides noise immunity and ensures stable operation.

Channels are independent of each other, meaning that SENSE1 and SENSE2 and respective outputs can be connected to different voltage rails.

9.3.2.1 SENSE Hysteresis

Built-in hysteresis to avoid erroneous output reset release. The hysteresis is opposite to the threshold voltage; for over-voltage options the hysteresis is subtracted from the positive threshold (V_{ITP}), for under-voltage options hysteresis is added to the negative threshold (V_{ITN}).

For all the hysteresis options possible see [Table 14-1](#)

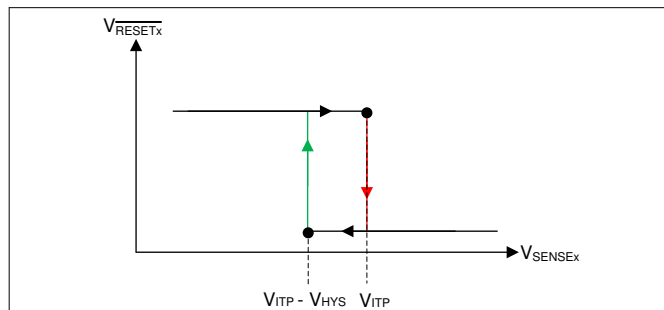


Figure 9-4. Hysteresis (Overvoltage Active-Low)

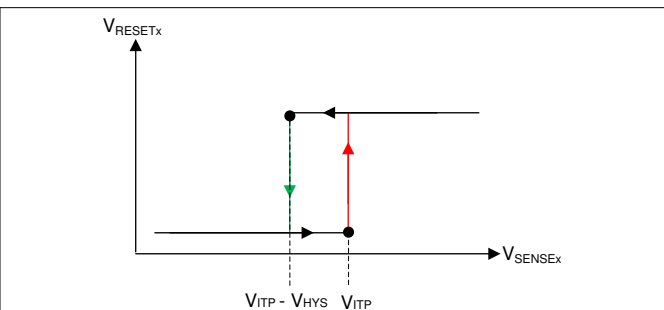


Figure 9-5. Hysteresis (Overvoltage Active-High)

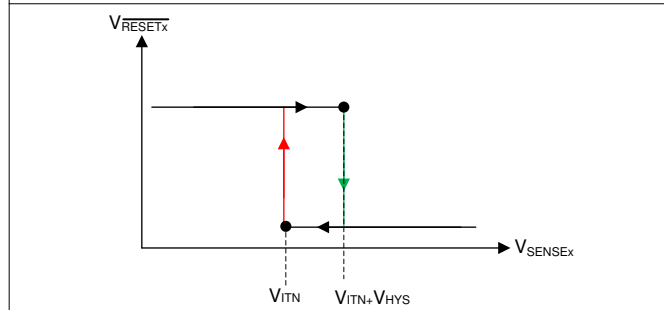


Figure 9-6. Hysteresis (Undervoltage Active-High)

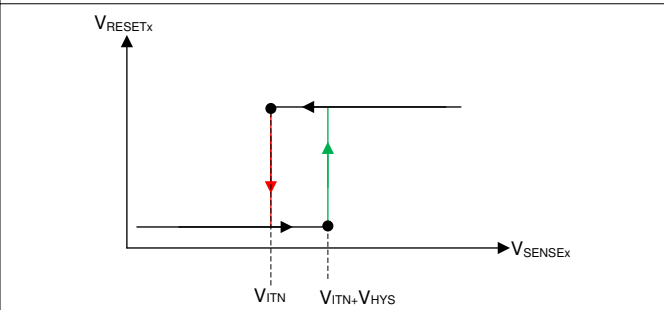


Figure 9-7. Hysteresis (Undervoltage Active-Low)

9.3.3 Output Logic Configurations

TPS38x has two channels with separate sense pins and reset pins that can be configured independently of each other. Channel 1 is available as Open-Drain and Push-Pull while channel 2 is only available as Open-Drain topology.

The available output logic configuration combinations are shown in Table [Table 9-1](#)

Table 9-1. TPS38x Output Logic

DESCRIPTION	NOMENCLATURE	VALUE	
		CHANNEL 1	CHANNEL 2
GPN Topology (OV and UV only) both channels are either OV or UV <ul style="list-style-type: none"> UV = Undervoltage OV = Overvoltage PP = Push Pull OD = Open Drain L = Active low H = Active high 	TPS38A	UV OD L	UV OD L
	TPS38B	UV PP L	UV OD L
	TPS38D	UV PP L	UV OD H
	TPS38E	UV PP H	UV OD H
	TPS38F	UV PP H	UV OD L
	TPS38G	UV OD H	UV OD H
	TPS38H	UV OD H	UV OD L
	TPS38J	OV OD L	OV OD L
	TPS38K	OV OD H	OV OD H
	TPS38L	OV OD H	OV OD L
	TPS38M	OV PP L	OV OD L
	TPS38N	OV PP L	OV OD H
	TPS38O	OV PP H	OV OD H
	TPS38P	OV PP H	OV OD L

9.3.3.1 Open-Drain

Open drain output requires a pull-up resistor to hold the voltage high to the required voltage logic. Connect the pull-up resistor to the proper voltage rail to enable the output to be connected to other devices at the correct interface voltage levels.

To select the right pull-up resistor consider system V_{OH} and the (I_{IKG}) current provided in the electrical characteristics, high resistors values will have a higher voltage drop affecting the output voltage high. The open-drain output can be connected as a wired-AND logic with other open-drain signals such as another TPS38X open-drain output pin.

9.3.3.2 Push-Pull

Push-Pull output does not require an external resistor since is the output is internally pulled-up to V_{DD} during V_{OH} condition and output will be connected to GND during V_{OH} condition.

9.3.3.3 Active-High (RESET)

RESET (active-high), denoted with no bar above the pin label. RESET remains low (V_{OL} , deasserted) as long as sense voltage is in normal operation within the threshold boundaries and VDD voltage is above UVLO. To assert a reset sense pins needs to meet the condition below:

- For under-voltage variant the SENSE voltage need to cross the lower boundary (V_{ITN}).
- For over-voltage variant the SENSE voltage needs to cross the upper boundary (V_{ITP}).

9.3.3.4 Active-Low ($\overline{\text{RESET}}$)

$\overline{\text{RESET}}$ (active low) denoted with a bar above the pin label. $\overline{\text{RESET}}$ remains high voltage (V_{OH} , deasserted) (open drain variant V_{OH} is measured against the pullup voltage) as long as sense voltage is in normal operation within the threshold boundaries and VDD voltage is above UVLO. To assert a reset sense pins needs to meet the condition below:

- For under-voltage variant the SENSE voltage need to cross the lower boundary (V_{ITN}).
- For over-voltage variant the SENSE voltage needs to cross the upper boundary (V_{ITP}).

9.3.4 User-programmable Reset Time Delay

TPS38X has adjustable reset release time delay with external capacitors. Channel timing are independent of each other.

- A capacitor in CTR1/MR program the reset time delay of Output 1.
- A capacitor in CTR2/MR program the reset time delay of Output 2.
- No capacitor on this pins gives the fastest reset delay time indicated in the [Section 7.6](#).

9.3.4.1 Reset Time Delay Configuration

The time delay (t_{CTR}) can be programmed by connecting a capacitor between CTR1 pin and GND, CTR2 for channel 2. In this section CTRx represent either channel 1 or channel 2.

The relationship between external capacitor C_{CTR_EXT} and the time delay (t_{CTR}) is given by [Equation 1](#).

$$t_{CTR} = 1.28 \times R_{CTR} \times C_{CTR_EXT} \quad (1)$$

R_{CTR} = is in kilo ohms (kOhms)

C_{CTR_EXT} = is given in microfarads (μF)

t_{CTR} = is in milliseconds (ms)

The recommended maximum reset delay capacitor for the TPS38x is limited to a percentage of the period or duration of the programmed reset time delay to ensure enough time for the capacitor to fully discharge when a voltage fault occurs. When a voltage fault occurs, the previously charged up capacitor discharges and if the monitored voltage returns from the fault condition before the delay capacitor discharges completely, the delay will be shorter than expected. The capacitor will begin charging from a voltage above zero and resulting in shorter than expected time delay. A larger delay capacitor can be used so long as the capacitor has enough time to fully discharge during the duration of the voltage fault. To ensure the capacitor is fully discharged, the time period or duration of the voltage fault needs to be greater than 5% of the programmed reset time delay.

9.3.5 User-Programmable Sense Delay

TPS38X has adjustable sense release time delay with external capacitors. Channel timing are independent of each other. Sense delay is used as a de-glitcher or ignoring known transients.

- A capacitor in CTS1 program the excursion detection on sense 1
- A capacitor in CTS2 program the excursion detection on sense 2
- No capacitor on these pins gives the fastest detection time indicated in the [Section 7.6](#).

9.3.5.1 Sense Time Delay Configuration

The time delay (t_{CTS}) can be programmed by connecting a capacitor between CTR1 pin and GND, CTS2 for channel 2. In this section CTRx represent either channel 1 or channel 2

The relationship between external capacitor C_{CTS_EXT} and the time delay (t_{CTSx}) is given by [Equation 2](#).

$$t_{CTSx} = 1.28 \times R_{CTSx} \times C_{CTSx_EXT} \quad (2)$$

R_{CTSx} = is in kilo ohms (kOhms)

C_{CTSx_EXT} = is given in microfarads (μF)

t_{CTSx} = is in milliseconds (ms)

The recommended maximum sense delay capacitor for the TPS38x is limited to a percentage of the period or duration of the programmed sense time delay to ensure enough time for the capacitor to fully discharge when a voltage fault occurs. When a voltage fault occurs, the previously charged up capacitor discharges and if the monitored voltage returns from the fault condition before the delay capacitor discharges completely, the delay will be shorter than expected. The capacitor will begin charging from a voltage above zero and resulting in shorter than expected time delay. A larger delay capacitor can be used so long as the capacitor has enough time to fully discharge during the duration of the voltage fault. To ensure the capacitor is fully discharged, the time period or duration of the voltage fault needs to be greater than 10% of the programmed sense time delay.

9.3.6 Manual RESET (CTR1/ $\overline{\text{MR}}$) and (CTR2/ $\overline{\text{MR}}$) Input

The manual reset input allows a processor or other logic circuits to initiate a reset. In this section $\overline{\text{MR}}$ is a generic reference to (CTR1/ $\overline{\text{MR}}$) and (CTR2/ $\overline{\text{MR}}$). A logic low on $\overline{\text{MR}}$ causes $\overline{\text{RESET1}}$ to assert on reset output. After $\overline{\text{MR}}$ is left floating, $\overline{\text{RESET1}}$ will release the reset if the voltage at SENSE1 pin is at nominal voltage. $\overline{\text{MR}}$ should not be driven high, this pin should be left floating or connected to a capacitor to GND, this pin can be left unconnected if is not used.

If the logic driving the $\overline{\text{MR}}$ cannot tri-state (floating and GND) then a logic-level FET should be used as illustrated in Figure 9-8.

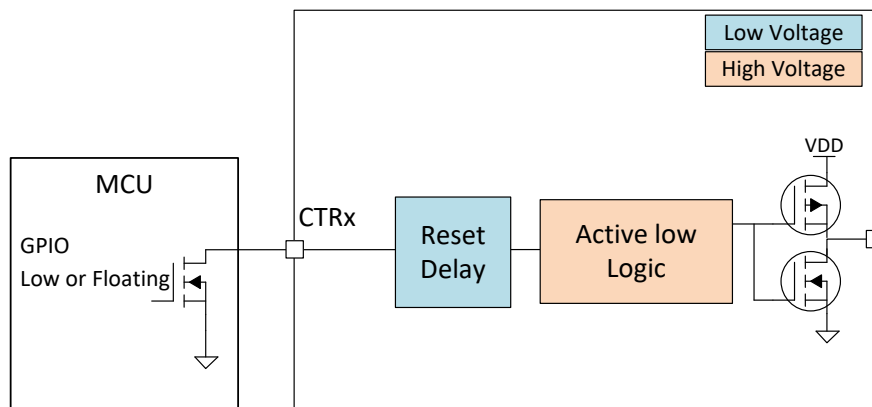


Figure 9-8. Manual Reset Implementation

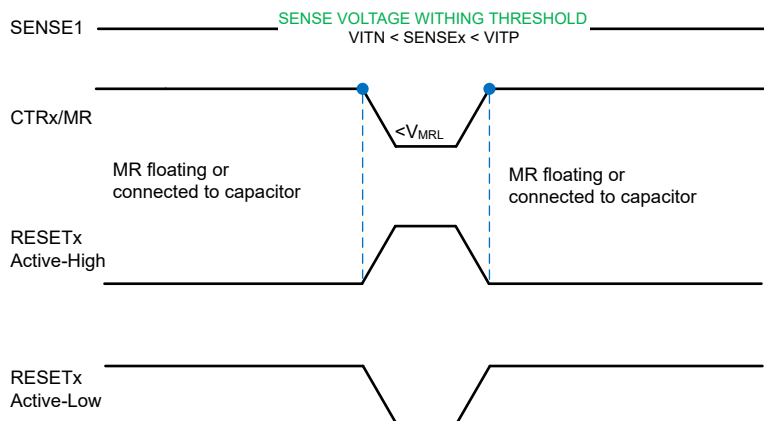


Figure 9-9. Manual Rest Timing Diagram

Table 9-2. $\overline{\text{MR}}$ Functional Table

$\overline{\text{MR}}$	SENSE ON NOMINAL VOLTAGE	Reset status
Low	Yes	Reset asserted
Floating	Yes	Reset release
Capacitor	Yes	Programable reset time delay
High (V_{IH_MR})	Yes	Reset release

10 Device Functional Modes

Table 10-1. Undervoltage Detect Functional Mode Truth Table

DESCRIPTION	SENSE		CTR ⁽¹⁾ / MR PIN	VDD PIN	OUTPUT ⁽²⁾ (RESET PIN)
	PREVIOUS CONDITION	CURRENT CONDITION			
Normal Operation	SENSE > V _{ITN(UV)}	SENSE > V _{ITN(UV)}	Open or capacitor connected	V _{DD} > V _{DD(MIN)}	High
Undervoltage Detection	SENSE > V _{ITN(UV)}	SENSE < V _{ITN(UV)}	Open or capacitor connected	V _{DD} > V _{DD(MIN)}	Low
Undervoltage Detection	SENSE < V _{ITN(UV)}	SENSE > V _{ITN(UV)}	Open or capacitor connected	V _{DD} > V _{DD(MIN)}	Low
Normal Operation	SENSE < V _{ITN(UV)}	SENSE > V _{ITN(UV)} + HYS	Open or capacitor connected	V _{DD} > V _{DD(MIN)}	High
Manual Reset	SENSE > V _{ITN(UV)}	SENSE > V _{ITN(UV)}	Low	V _{DD} > V _{DD(MIN)}	Low
UVLO Engaged	SENSE > V _{ITN(UV)}	SENSE > V _{ITN(UV)}	Open or capacitor connected	V _{POR} < V _{DD} < V _{DD(MIN)}	Low
Below V _{POR} , Undefined Output	SENSE > V _{ITN(UV)}	SENSE > V _{ITN(UV)}	Open or capacitor connected	V _{DD} < V _{POR}	Undefined

- Reset time delay is ignored in the truth table
- Open-drain active low output. External pull-up resistor to high voltage

Table 10-2. Overvoltage Detect Functional Mode Truth Table

DESCRIPTION	SENSE		CTR ⁽¹⁾ / MR PIN	VDD PIN	OUTPUT ⁽²⁾ (RESET PIN)
	PREVIOUS CONDITION	CURRENT CONDITION			
Normal Operation	SENSE < V _{ITN(OV)}	SENSE < V _{ITN(OV)}	Open or capacitor connected	V _{DD} > V _{DD(MIN)}	High
Undervoltage Detection	SENSE < V _{ITN(OV)}	SENSE > V _{ITN(OV)}	Open or capacitor connected	V _{DD} > V _{DD(MIN)}	Low
Undervoltage Detection	SENSE > V _{ITN(OV)}	SENSE < V _{ITN(OV)}	Open or capacitor connected	V _{DD} > V _{DD(MIN)}	Low
Normal Operation	SENSE > V _{ITN(OV)}	SENSE < V _{ITN(OV)} - HYS	Open or capacitor connected	V _{DD} > V _{DD(MIN)}	High
Manual Reset	SENSE < V _{ITN(OV)}	SENSE < V _{ITN(OV)}	Low	V _{DD} > V _{DD(MIN)}	Low
UVLO Engaged	SENSE < V _{ITN(OV)}	SENSE < V _{ITN(OV)}	Open or capacitor connected	V _{POR} < V _{DD} < UVLO	Low
Below V _{POR} , Undefined Output	SENSE < V _{ITN(OV)}	SENSE < V _{ITN(OV)}	Open or capacitor connected	V _{DD} < V _{POR}	Undefined

- Reset time delay is ignored in the truth table
- Open-drain active low output. External pull-up resistor to high voltage

11 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

11.1 Adjustable Voltage Thresholds

[Equation 3](#) illustrates an example of how to adjust the voltage threshold with external resistor dividers. The resistors can be calculated depending on the desired voltage threshold and device part number. TI recommends using the 0.8 V voltage threshold device when using an adjustable voltage variant. This variant bypasses the internal resistor ladder.

For example, consider a 2.0 V rail being monitored (V_{MON}) using. Using [Equation 3](#), $R_1 = 15\text{ k}\Omega$ given that $R_2 = 10\text{ k}\Omega$, $V_{MON} = 2\text{ V}$, and $V_{SENSE} = 0.8\text{ V}$. Using [Equation 3](#), $V_{MON} = 1.94\text{ V}$ when $V_{SENSE} = V_{IT-(UV)}$. This can be denoted as V_{MON-} , the monitored undervoltage threshold where the device will assert a reset signal.

$$V_{SENSE} = V_{MON} \times (R_2 \div (R_1 + R_2)) \quad (3)$$

Aside from the tolerance of the resistor divider, the SENSE pin leakage current affects the accuracy of the resistor divider. The sense leakage, I_{SENSE} , is given in [Section 7.5](#). The actual input threshold due to the leakage SENSE current can be calculated with [Equation 4](#)

$$I_{VIT_Actual} = V_{MON} + R_1 ((V_{REF} \div R_2) + I_{SENSE}) \quad (4)$$

11.2 Application Information

The following sections describe in detail how to properly use this device, depending on the requirements of the final application.

11.3 Typical Application

11.3.1 Design 1: Automotive Off-Battery Monitoring

The initial power stage in automotive applications starts with the 12 V battery. Variation of the battery voltage is common between 9 V and 16 V. Furthermore, if cold-cranking and load dump conditions are considered, voltage transients can occur as low as 3 V and as high as 42 V. In this design example, we are highlighting the ability for low power, direct off-battery voltage supervision. [Figure 11-1](#) illustrates an example of how the TPS38x-Q1 is monitoring the battery voltage while being powered by it as well. For more information, read this [application report](#) on how to achieve low I_Q voltage supervision in automotive, wide- V_{IN} applications.

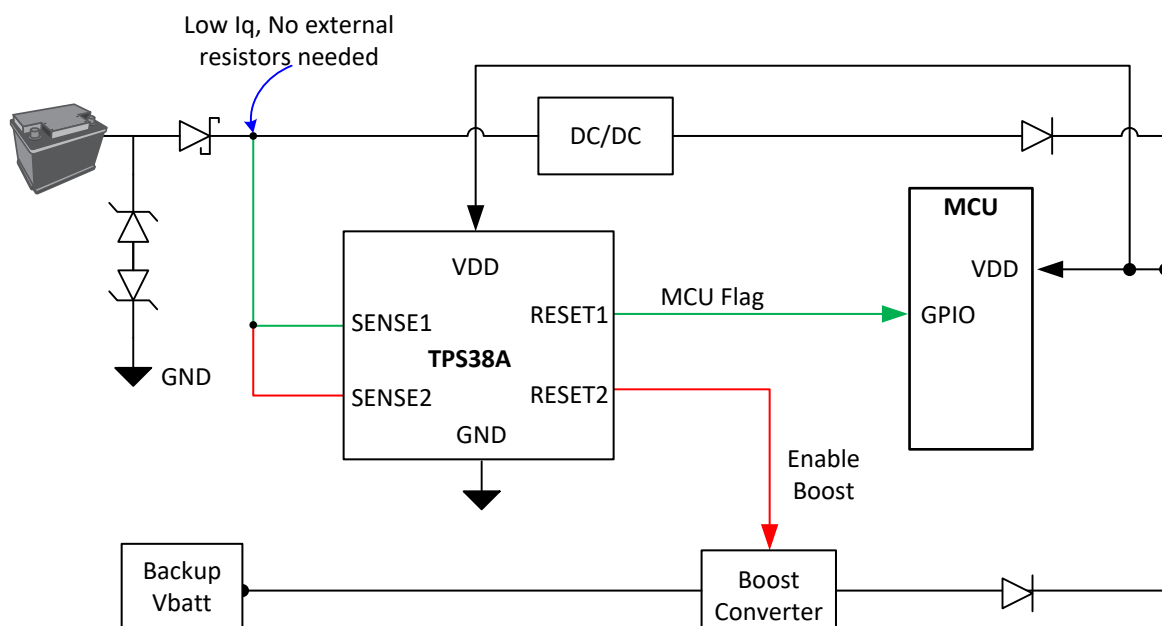


Figure 11-1. Fast Start Supervisor with Direct Off-Battery Monitoring

11.3.1.1 Design Requirements

This design requires voltage supervision on a 12-V power supply voltage rail with possibility of the 12-V rail rising up as high as 42 V. The undervoltage fault occurs when the power supply voltage drops below 7.7 V.

PARAMETER	DESIGN REQUIREMENT	DESIGN RESULT
Power Rail Voltage Supervision	Monitor 12-V power supply for undervoltage condition, trigger a undervoltage fault at 7.7 V.	TPS38x-Q1 provides voltage monitoring with 1.5% max accuracy with adjustable/non-adjustable variations.
Maximum Input Power	Operate with power supply input up to 42 V.	The TPS38x-Q1 can support a VDD of up to 65 V.
Output logic voltage	Open-Drain Output Topology	An open-drain output is recommended to provide the correct reset signal, but a push-pull can also be used.
Maximum system current consumption	2 μ A max when power supply is at 12 V typical	TPS38x-Q1 allows for I_Q to remain low with support of up to 65 V. This allows for no external resistor divider to be required.
Voltage Monitor Accuracy	Maximum voltage monitor accuracy of 1.5%.	The TPS38x-Q1 has 1.5% maximum voltage monitor accuracy.
Delay when returning from fault condition	RESET delay of at least 420 ms when returning from a undervoltage fault.	$C_{CTR} = .033 \mu$ F sets 422 ms delay

11.3.1.2 Detailed Design Procedure

The primary advantage of this application is being able to monitor a voltage on an automotive battery without needing external resistors on the input. This keeps I_Q low while still achieving the desired rail monitoring.

As shown in [Figure 11-1](#), the rail monitoring can be done directly with the SENSE1 and SENSE2 inputs directly connected to the battery rail after the protection diodes.

To use this configuration, the specific voltage threshold variation of the device must be chosen according to the application. In this configuration, the '77' variation must be chosen for 7.7 V as shown in [Table 14-2](#).

The device being able to handle 65 V on VDD means the monitored voltage rail can go as high as 42 V for the application transients and not violate the recommended maximum for the supervisor as it usually would. This is useful when monitoring a voltage rail that has a wide range that may go much higher than the nominal rail voltage such as in this case. Good design practice recommends using a 0.1- μ F capacitor on the VDD pin and this capacitance may need to increase if using an adjustable version with a resistor divider.

12 Power Supply Recommendations

These devices are designed to operate from an input supply with a voltage range between 1.4 V (V_{POR}) to 65 V (max operation). Good analog design practice recommends placing a minimum 0.1-μF ceramic capacitor as near as possible to the VDD pin.

12.1 Power Dissipation and Device Operation

The permissible power dissipation for any package is a measure of the capability of the device to pass heat from the power source, the junctions of the IC, to the ultimate heat sink, the ambient environment. Thus, the power dissipation is dependent on the ambient temperature and the thermal resistance across the various interfaces between the die junction and ambient air.

The maximum continuous allowable power dissipation for the device in a given package can be calculated using [Equation 5](#):

$$P_{D-MAX} = ((T_{J-MAX} - T_A) / R_{\theta JA}) \quad (5)$$

The actual power being dissipated in the device can be represented by [Equation 6](#):

$$P_D = V_{DD} \times I_{DD} + P_{RESET} \quad (6)$$

P_{RESET} is calculated by [Equation 7](#) or [Equation 8](#)

$$P_{RESET} (PUSH/PULL) = V_{DD} - V_{RESET} \times I_{RESET} \quad (7)$$

$$P_{RESET} (OPEN-DRAIN) = V_{RESET} \times I_{RESET} \quad (8)$$

[Equation 5](#) and [Equation 6](#) establish the relationship between the maximum power dissipation allowed due to thermal consideration, the voltage drop across the device, and the continuous current capability of the device. These two equations should be used to determine the optimum operating conditions for the device in the application.

In applications where lower power dissipation (P_D) and/or excellent package thermal resistance ($R_{\theta JA}$) is present, the maximum ambient temperature (T_{A-MAX}) may be increased.

In applications where high power dissipation and/or poor package thermal resistance is present, the maximum ambient temperature (T_{A-MAX}) may have to be derated. T_{A-MAX} is dependent on the maximum operating junction temperature ($T_{J-MAX-OP} = 125^\circ\text{C}$), the maximum allowable power dissipation in the device package in the application (P_{D-MAX}), and the junction-to ambient thermal resistance of the part/package in the application ($R_{\theta JA}$), as given by [Equation 9](#):

$$T_{A-MAX} = (T_{J-MAX-OP} - (R_{\theta JA} \times P_{D-MAX})) \quad (9)$$

13 Layout

13.1 Layout Guidelines

- Make sure that the connection to the VDD pin is low impedance. Good analog design practice is to place a greater than 0.1- μ F ceramic capacitor as near as possible to the VDD pin.
- If a capacitor is used on CTS1, CTS2, CTR1, or CTR2, place these components as close as possible to the respective pins. If the capacitor adjustable pins are left unconnected, make sure to minimize the amount of parasitic capacitance on the pins to less than 5 pF.
- Place the pull-up resistors on $\overline{\text{RESET1}}$ and $\overline{\text{RESET2}}$ pins as close to the pins as possible.

13.2 Layout Example

The layout example in [Figure 13-1](#) shows how the TPS38x-Q1 is laid out on a printed circuit board (PCB) with user-defined delays.

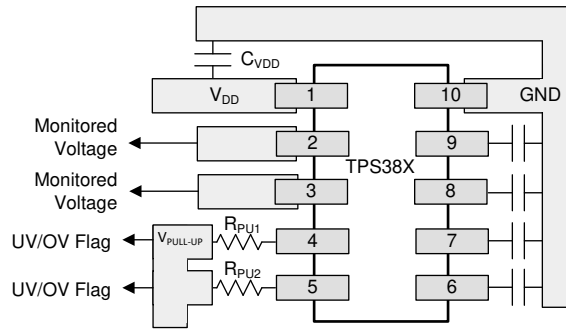


Figure 13-1. TPS38x-Q1 Recommended Layout

13.3 Creepage Distance

Per IEC 60664 Creepage is the shortest distance between two conductive parts or as shown in [Figure 13-2](#) the distance between high voltage conductive parts and grounded parts, the floating conductive part is ignored and subtracted from the total distance.

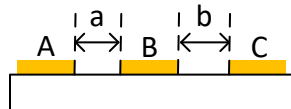


Figure 13-2. Creepage Distance

[Figure 13-2](#) details

- A = Left pins (high voltage)
- B = Central pad (conductive not internally connected)
- C = Right pins (low voltages)
- Creepage distance = $a + b$

14 Device and Documentation Support

14.1 Device Nomenclature

Section 5 shows how to decode the function of the device based on its part number

Table 14-2 shows TPS38x possible voltage options per channel. Contact TI sales representatives or on TI's E2E forum for details and availability of other options; minimum order quantities apply.

Table 14-1 shows TPS38x common hysteresis and voltage options.

Table 14-1. Common Hysteresis Lookup Table

TARGET			DEVICE ACTUAL HYSTERESIS OPTION
DETECT THRESHOLD	TOPOLOGY	RELEASE VOLTAGE (V)	
18.0 V	Over-voltage	17.5 V	-3%
18.0 V	Over-voltage	16.0 V	-11%
17.0 V	Over-voltage	16.5 V	-3%
16.0 V	Over-voltage	15.0 V	-6%
15.0 V	Over-voltage	14.0 V	-7%
6.0 V	Under-Voltage	6.5 V	0.5 V
5.5 V	Under-Voltage	6 V	0.5 V
8 V	Under-Voltage	9 V	1 V
5 V	Under-Voltage	7.5 V	2.5 V

Table 14-2. Voltage Options

100 mV STEPS				400 mV STEPS		500 mV STEPS		1 V STEPS	
NOMEN- CLATURE	VOLTAGE OPTIONS	NOMEN- CLATURE	VOLTAGE OPTIONS	NOMEN- CLATURE	VOLTAGE OPTIONS	NOMEN- CLATURE	VOLTAGE OPTIONS	NOMEN- CLATURE	VOLTAGE OPTIONS
08	800 mV (divider bypass)	70	7.0 V	A0	10.4 V	D0	20.5 V	F0	31.0 V
27	2.7 V	71	7.1 V	A1	10.8 V	D1	21.0 V	F1	32.0 V
28	2.8 V	72	7.2 V	A2	11.2 V	D2	21.5 V	F2	33.0 V
29	2.9 V	73	7.3 V	A3	11.6 V	D3	22.0 V	F3	34.0 V
30	3.0 V	74	7.4 V	A4	12.0 V	D4	22.5 V	F4	35.0 V
31	3.1 V	75	7.5 V	A5	12.4 V	D5	23.0 V	F5	36.0 V
32	3.2 V	76	7.6 V	A6	12.8 V	D6	23.5 V		
33	3.3 V	77	7.7 V	A7	13.2 V	D7	24.0 V		
34	3.4 V	78	7.8 V	A8	13.6 V	D8	24.5 V		
35	3.5 V	79	7.9 V	A9	14.0 V	D9	25.0 V		
36	3.6 V	80	8.0 V	B0	14.4 V	E0	25.5 V		
37	3.7 V	81	8.1 V	B1	14.8 V	E1	26.0 V		
38	3.8 V	82	8.2 V	B2	15.2 V	E2	26.5 V		
39	3.9 V	83	8.3 V	B3	15.6 V	E3	27.0 V		
40	4.0 V	84	8.4 V	B4	16.0 V	E4	27.5 V		
41	4.1 V	85	8.5 V	B5	16.4 V	E5	28.0 V		
42	4.2 V	86	8.6 V	B6	16.8 V	E6	28.5 V		
43	4.3 V	87	8.7 V	B7	17.2 V	E7	29.0 V		
44	4.4 V	88	8.8 V	B8	17.6 V	E8	29.5 V		
45	4.5 V	89	8.9 V	B9	18.0 V	E9	30.0 V		
46	4.6 V	90	9.0 V	C0	18.4 V				
47	4.7 V	91	9.1 V	C1	18.8 V				
48	4.8 V	92	9.2 V	C2	19.2 V				
49	4.9 V	93	9.3 V	C3	19.6 V				
50	5.0 V	94	9.4 V	C4	20.0 V				
51	5.1 V	95	9.5 V						
52	5.2 V	96	9.6 V						
53	5.3 V	97	9.7 V						
54	5.4 V	98	9.8 V						
55	5.5 V	99	9.9 V						
56	5.6 V	00	10.0 V						
57	5.7 V								
58	5.8 V								
59	5.9 V								
60	6.0 V								
61	6.1 V								
62	6.2 V								
63	6.3 V								
64	6.4 V								
65	6.5 V								
66	6.6 V								
67	6.7 V								

Table 14-2. Voltage Options (continued)

100 mV STEPS				400 mV STEPS		500 mV STEPS		1 V STEPS	
NOMEN- CLATURE	VOLTAGE OPTIONS	NOMEN- CLATURE	VOLTAGE OPTIONS	NOMEN- CLATURE	VOLTAGE OPTIONS	NOMEN- CLATURE	VOLTAGE OPTIONS	NOMEN- CLATURE	VOLTAGE OPTIONS
68	6.8 V								
69	6.9 V								

14.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

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14.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

14.5 Glossary

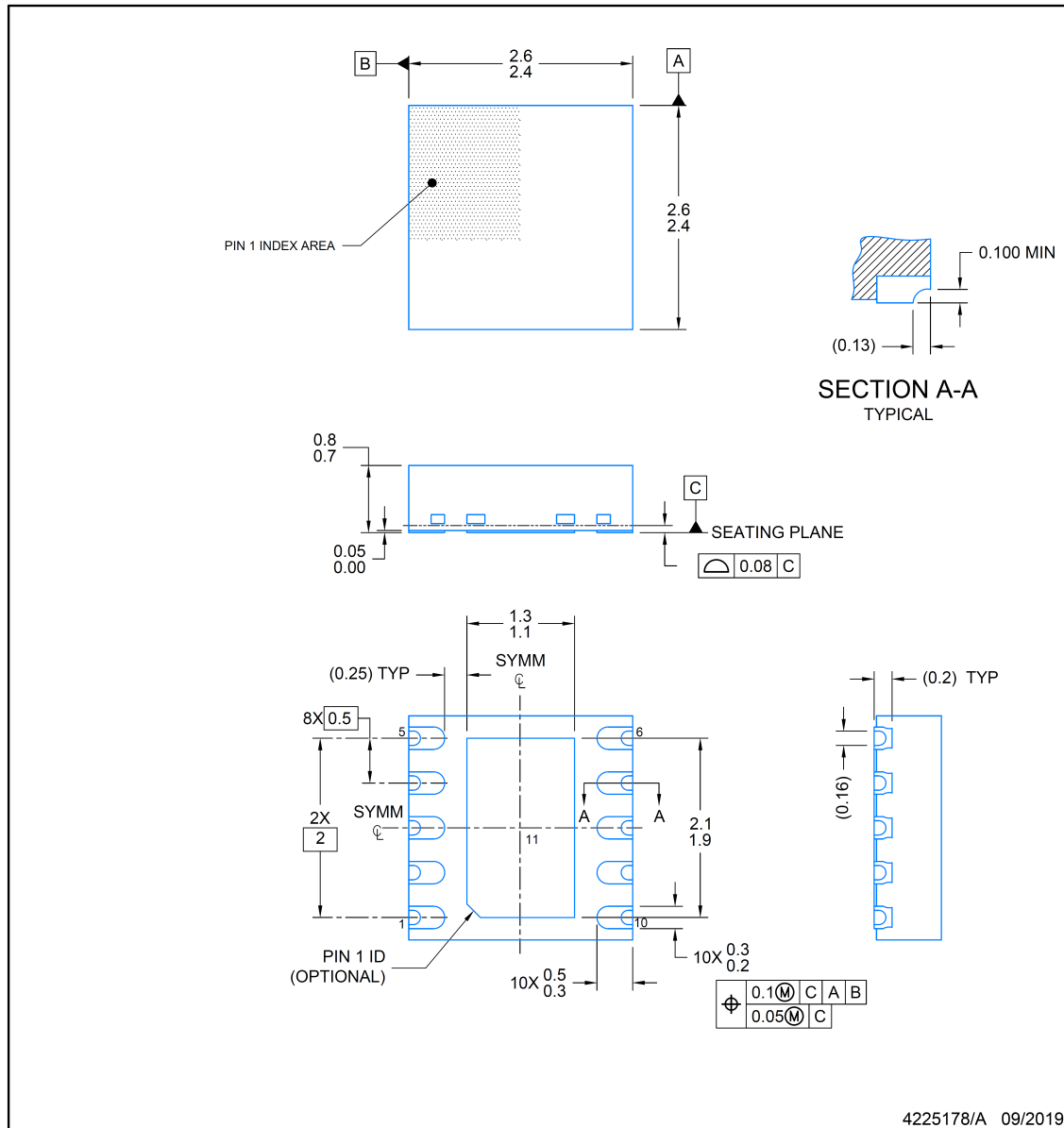
[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

15 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

DSK0010C
PACKAGE OUTLINE
WSN - 0.8 mm max height

PLASTIC QUAD FLAT PACK- NO LEAD

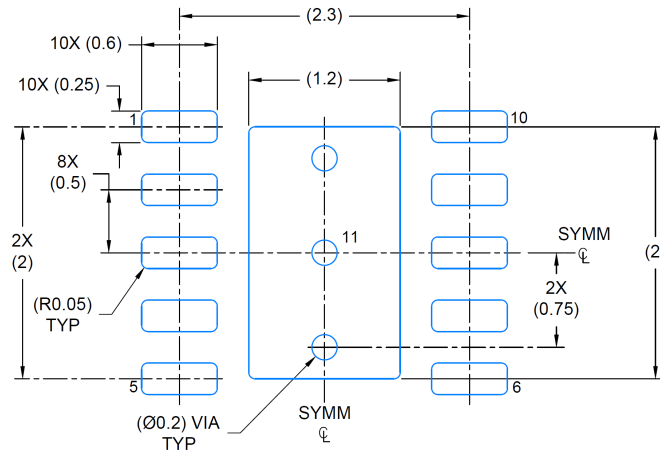


EXAMPLE BOARD LAYOUT

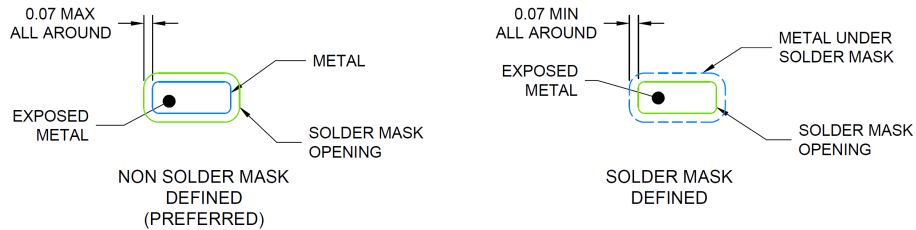
DSK0010C

WSON - 0.8 mm max height

PLASTIC QUAD FLAT PACK- NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



SOLDER MASK DETAILS

4225178/A 09/2019

NOTES: (continued)

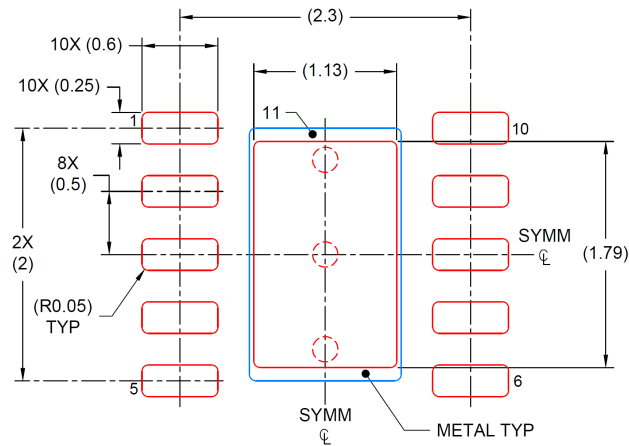
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

WSN - 0.8 mm max height

PLASTIC QUAD FLAT PACK- NO LEAD

DSK0010C



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
84% PRINTED COVERAGE BY AREA
SCALE: 20X

4225178/A 09/2019

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
PS38A950122DSKRQ1	ACTIVE	SON	DSK	10	3000	Non-RoHS & Non-Green	Call TI	Call TI	-40 to 125		Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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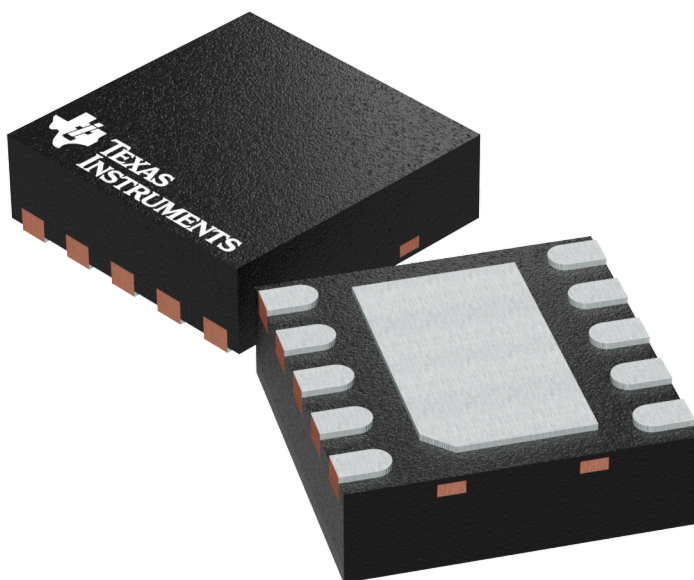
GENERIC PACKAGE VIEW

DSK 10

WSON - 0.8 mm max height

2.5 x 2.5 mm, 0.5 mm pitch

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4225304/A

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